

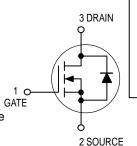
Low rDS(on) Small-Signal MOSFETs TMOS Single N-Channel Field Effect Transistor

Part of the GreenLine™ Portfolio of devices with energy–conserving traits.

These miniature surface mount MOSFETs utilize Motorola's High Cell Density, HDTMOS process. Low rDS(on) assures minimal power loss and conserves energy, making this device ideal for use in space sensitive power management circuitry. Typical applications are dc–dc converters and power management in portable and battery–powered products such as computers, printers, PCMCIA cards, cellular and cordless telephones.

- Low r_{DS(on)} Provides Higher Efficiency and Extends Battery Life
- Miniature SOT-23 Surface Mount Package Saves Board Space





N-CHANNEL LOGIC LEVEL

ENHANCEMENT-MODE

TMOS MOSFET

MGSF1N02ELT1

Motorola Preferred Device



MAXIMUM RATINGS (T_J = 25°C unless otherwise noted)

Rating		Value	Unit
Drain-to-Source Voltage	VDSS	20	Vdc
Gate-to-Source Voltage — Continuous	V _{GS}	± 8.0	Vdc
Drain Current — Continuous @ T _A = 25°C — Pulsed Drain Current (t _p ≤ 10 μs)	I _D	750 2000	mA
Total Power Dissipation @ T _A = 25°C	PD	400	mW
Operating and Storage Temperature Range	TJ, T _{stg}	- 55 to 150	°C
Thermal Resistance — Junction–to–Ambient	$R_{\theta JA}$	300	°C/W
Maximum Lead Temperature for Soldering Purposes, 1/8" from case for 10 seconds	TL	260	°C

ORDERING INFORMATION

Device	Reel Size	Tape Width	Quantity
MGSF1N02ELT1	7″	8mm embossed tape	3000
MGSF1N02ELT3	13″	8mm embossed tape	10,000

GreenLine is a trademark of Motorola, Inc.

HDTMOS is a trademark of Motorola, Inc. TMOS is a registered trademark of Motorola, Inc.

Thermal Clad is a trademark of the Bergquist Company.

Preferred devices are Motorola recommended choices for future use and best overall value.



MGSF1N02ELT1

ELECTRICAL CHARACTERISTICS (T_A = 25°C unless otherwise noted)

Characteristic			Min	Тур	Max	Unit
OFF CHARACTERISTICS						•
Drain-to-Source Breakdown Voltage (V _{GS} = 0 Vdc, I _D = 10 μA)		V _{(BR)DSS}	20	_	_	Vdc
Zero Gate Voltage Drain Current (VDS = 20 Vdc, VGS = 0 Vdc) (VDS = 20 Vdc, VGS = 0 Vdc, TJ = 125°C)		IDSS	_	_	1.0 10	μAdc
Gate-Source Leakage Current (VGS	= ± 8.0 Vdc, V _{DS} = 0 Vdc)	IGSS	_	_	±0.1	μAdc
ON CHARACTERISTICS(1)						
Gate–Source Threshold Voltage (VDS = VGS, ID = 250 μAdc)		V _{GS(th)}	0.5	_	1.0	Vdc
Static Drain–to–Source On–Resistance ($V_{GS} = 4.5 \text{ Vdc}$, $I_{D} = 1.0 \text{ A}$) ($V_{GS} = 2.5 \text{ Vdc}$, $I_{D} = 0.75 \text{ A}$)		rDS(on)	_		0.085 0.115	Ohms
DYNAMIC CHARACTERISTICS						
Input Capacitance	$(V_{DS} = 5.0 \text{ Vdc}, V_{GS} = 0 \text{ V}, f = 1.0 \text{ Mhz})$	C _{iss}	_	160	_	pF
Output Capacitance	$(V_{DS} = 5.0 \text{ Vdc}, V_{GS} = 0 \text{ V}, f = 1.0 \text{ Mhz})$	C _{oss}	_	130	_	
Transfer Capacitance	$(V_{DG} = 5.0 \text{ Vdc}, V_{GS} = 0 \text{ V}, f = 1.0 \text{ Mhz})$	C _{rss}	_	60	_	
SWITCHING CHARACTERISTICS(2)				•		
Turn-On Delay Time		^t d(on)	_	6.0	_	ns
Rise Time	$(V_{DD} = 5 \text{ Vdc}, I_{D} = 1.0 \text{ Adc},$	t _r	_	26	_	
Turn-Off Delay Time	$R_L = 5 \Omega$, $R_G = 6 \Omega$)	^t d(off)	_	117	_	
Fall Time		tf	_	105	_	
Total Gate Charge	$(V_{DS} = 16 \text{ Vdc}, I_{D} = 1.2 \text{ Adc}, V_{GS} = 4.0 \text{ Vdc})$	QT	_	6500	_	рC
SOURCE-DRAIN DIODE CHARACTE	RISTICS					
Continuous Current		IS	_	_	0.6	А
Pulsed Current		I _{SM}	_	_	0.75	
Forward Voltage ⁽²⁾ (V _{GS} = 0 Vdc, I _S = 0.6 Adc)		V_{SD}	_	_	1.2	V

⁽¹⁾ Pulse Test: Pulse Width \leq 300 μ s, Duty Cycle \leq 2%.

TYPICAL ELECTRICAL CHARACTERISTICS

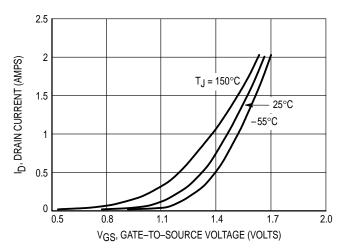


Figure 1. Transfer Characteristics

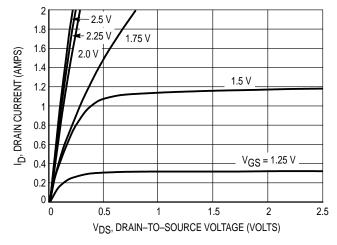


Figure 2. On-Region Characteristics

⁽²⁾ Switching characteristics are independent of operating junction temperature.

MGSF1N02ELT1

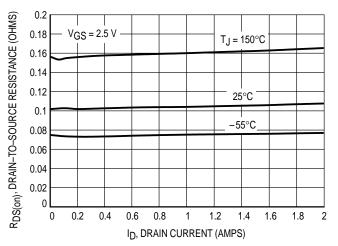


Figure 3. On-Resistance versus Drain Current

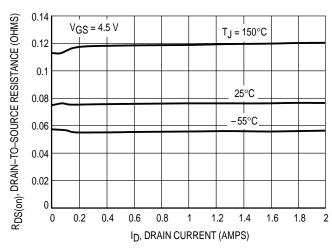


Figure 4. On-Resistance versus Drain Current

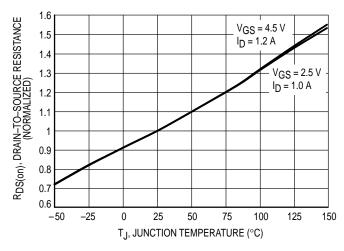


Figure 5. On–Resistance Variation Over Temperature

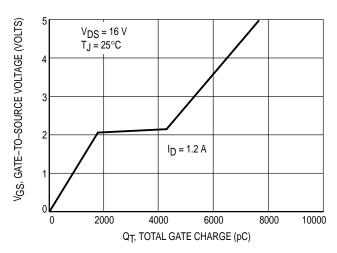


Figure 6. Gate Charge

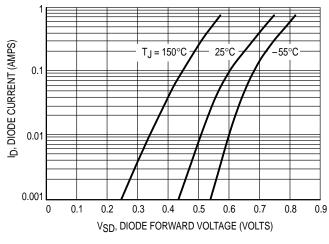


Figure 7. Body Diode Forward Voltage

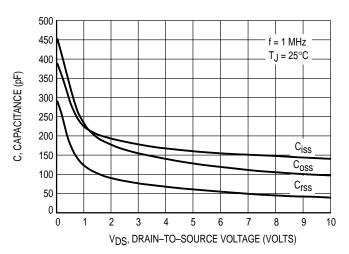
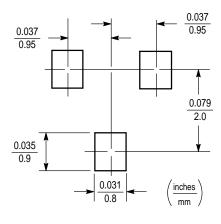


Figure 8. Capacitance Variation

INFORMATION FOR USING THE SOT-23 SURFACE MOUNT PACKAGE

MINIMUM RECOMMENDED FOOTPRINT FOR SURFACE MOUNTED APPLICATIONS

Surface mount board layout is a critical portion of the total design. The footprint for the semiconductor packages must be the correct size to insure proper solder connection interface between the board and the package. With the correct pad geometry, the packages will self align when subjected to a solder reflow process.



SOT-23

SOT-23 POWER DISSIPATION

The power dissipation of the SOT–23 is a function of the drain pad size. This can vary from the minimum pad size for soldering to a pad size given for maximum power dissipation. Power dissipation for a surface mount device is determined by $\mathsf{T}_{J(max)}$, the maximum rated junction temperature of the die, $\mathsf{R}_{\theta JA}$, the thermal resistance from the device junction to ambient, and the operating temperature, T_A . Using the values provided on the data sheet for the SOT–23 package, P_D can be calculated as follows:

$$P_D = \frac{T_{J(max)} - T_A}{R_{\theta,JA}}$$

The values for the equation are found in the maximum ratings table on the data sheet. Substituting these values into the equation for an ambient temperature T_A of $25^{\circ}C$, one can calculate the power dissipation of the device which in this case is 416 milliwatts.

$$P_D = \frac{150^{\circ}C - 25^{\circ}C}{300^{\circ}C/W} = 416 \text{ milliwatts}$$

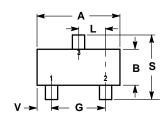
The 300°C/W for the SOT–23 package assumes the use of the recommended footprint on a glass epoxy printed circuit board to achieve a power dissipation of 416 milliwatts. There are other alternatives to achieving higher power dissipation from the SOT–23 package. Another alternative would be to use a ceramic substrate or an aluminum core board such as Thermal Clad™. Using a board material such as Thermal Clad, an aluminum core board, the power dissipation can be doubled using the same footprint.

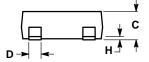
SOLDERING PRECAUTIONS

The melting temperature of solder is higher than the rated temperature of the device. When the entire device is heated to a high temperature, failure to complete soldering within a short time could result in device failure. Therefore, the following items should always be observed in order to minimize the thermal stress to which the devices are subjected.

- Always preheat the device.
- The delta temperature between the preheat and soldering should be 100°C or less.*
- When preheating and soldering, the temperature of the leads and the case must not exceed the maximum temperature ratings as shown on the data sheet. When using infrared heating with the reflow soldering method, the difference shall be a maximum of 10°C.
- The soldering temperature and time shall not exceed 260°C for more than 10 seconds.
- When shifting from preheating to soldering, the maximum temperature gradient shall be 5°C or less.
- After soldering has been completed, the device should be allowed to cool naturally for at least three minutes.
 Gradual cooling should be used as the use of forced cooling will increase the temperature gradient and result in latent failure due to mechanical stress.
- Mechanical stress or shock should not be applied during cooling.
- * Soldering a device without preheating can cause excessive thermal shock and stress which can result in damage to the device.

PACKAGE DIMENSIONS







CASE 318-08 **ISSUE AE** SOT-23 (TO-236AB)

- 1. DIMENSIONING AND TOLERANCING PER ANSI Y14.5M, 1982.
- CONTROLLING DIMENSION: INCH.
 MAXIMUM LEAD THICKNESS INCLUDES LEAD FINISH THICKNESS. MINIMUM LEAD THICKNESS IS THE MINIMUM THICKNESS OF BASE MATERIAL.

	INCHES		MILLIMETERS		
DIM	MIN	MAX	MIN	MAX	
Α	0.1102	0.1197	2.80	3.04	
В	0.0472	0.0551	1.20	1.40	
С	0.0350	0.0440	0.89	1.11	
D	0.0150	0.0200	0.37	0.50	
G	0.0701	0.0807	1.78	2.04	
Н	0.0005	0.0040	0.013	0.100	
J	0.0034	0.0070	0.085	0.177	
K	0.0180	0.0236	0.45	0.60	
L	0.0350	0.0401	0.89	1.02	
S	0.0830	0.0984	2.10	2.50	
٧	0.0177	0.0236	0.45	0.60	

STYLE 21: PIN 1. GATE

SOURCE
 DRAIN

Motorola reserves the right to make changes without further notice to any products herein. Motorola makes no warranty, representation or guarantee regarding the suitability of its products for any particular purpose, nor does Motorola assume any liability arising out of the application or use of any product or circuit, and specifically disclaims any and all liability, including without limitation consequential or incidental damages. "Typical" parameters which may be provided in Motorola data sheets and/or specifications can and do vary in different applications and actual performance may vary over time. All operating parameters, including "Typicals" must be validated for each customer application by customer's technical experts. Motorola does not convey any license under its patent rights nor the rights of others. Motorola products are not designed, intended, or authorized for use as components in systems intended for surgical implant into the body, or other applications intended to support or sustain life, or for any other application in which the failure of the Motorola product could create a situation where personal injury or death may occur. Should Buyer purchase or use Motorola products for any such unintended or unauthorized application, Buyer shall indemnify and hold Motorola and its officers, employees, subsidiaries, affiliates, and distributors harmless against all claims, costs, damages, and expenses, and reasonable attorney fees arising out of, directly or indirectly, any claim of personal injury or death associated with such unintended or unauthorized use, even if such claim alleges that Motorola was negligent regarding the design or manufacture of the part. Motorola and 祸 are registered trademarks of Motorola, Inc. Motorola, Inc. is an Equal Opportunity/Affirmative Action Employer.

This device has a class 1 ESD rating.

Mfax is a trademark of Motorola. Inc.

How to reach us:

USA/EUROPE/Locations Not Listed: Motorola Literature Distribution; JAPAN: Nippon Motorola Ltd.: SPD, Strategic Planning Office, 141, P.O. Box 5405, Denver, Colorado 80217. 1-303-675-2140 or 1-800-441-2447 4-32-1 Nishi-Gotanda, Shagawa-ku, Tokyo, Japan. 03-5487-8488

Customer Focus Center: 1-800-521-6274

Mfax™: RMFAX0@email.sps.mot.com - TOUCHTONE 1-602-244-6609 ASIA/PACIFIC: Motorola Semiconductors H.K. Ltd.; 8B Tai Ping Industrial Park, - US & Canada ONLY 1-800-774-1848 Motorola Fax Back System 51 Ting Kok Road, Tai Po, N.T., Hong Kong. 852–26629298

- http://sps.motorola.com/mfax/

 \Diamond

HOME PAGE: http://motorola.com/sps/



MGSF1N02ELT1/D